

TRANSPORTATION



AIM solder paste is shipped in specially designed packaging which maintains the product temperature between 0°-30°C (32°-84°F) for a minimum of 48 hours depending on external conditions. Solder paste should be shipped via overnight service or refrigerated transport. Extended transport time in high temperature environments must be avoided. Cold packs used as part of paste packaging may arrive melted. This is normal and not an indication of mishandling or damage if 48 hour transport time is not exceeded.

STORAGE



Solder paste should be transferred immediately to controlled storage on receipt.

Refrigeration is recommended but may not be required. AIM solder pastes typically have a shelf life of three to six months when stored at room temperature (22°C/72°F). Refrigerated: 0°-12°C (32°F-55°F) / Unrefrigerated < 25°C (< 77°F). Refer to the product-specific TDS for additional shelf life information. Solder paste performance may be affected if exposed to temperatures exceeding 30°C (85°F). Do not expose solder paste to temperatures exceeding 32°C (90°F).

Solder paste in cartridges or syringe packaging should be stored vertically, tip down when possible. If stored horizontally, packages should be periodically rotated 180°.

Date of Manufacture (DOM) is noted on the paste label; paste should be used before the expiration period found on the product specific TDS. Oldest solder paste lots should be used first, on a First-In First-Out (FIFO) system with date and time of removal from storage recorded.

PREPARATION FOR USE

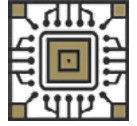


Solder paste must NEVER be used cold. Solder paste must be allowed to reach ambient temperature, 68°-77°F (20°-25°C), before breaking the seal of the paste package. This typically takes four to six hours. **DO NOT FORCE WARM THE PASTE.**

Once the solder paste has reached ambient temperature paste in jars should be stirred with a plastic tool lightly and thoroughly for one minute or more. Solder paste in syringes and cartridges does not require mixing. Use of automated solder paste mixing equipment is not recommended and may damage solder paste.

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STENCIL APPLICATION



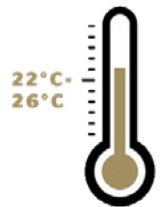
DO NOT combine new and used solder paste in the same container. This will contaminate and degrade unused paste.

Paste should not be re-refrigerated after opening. Any opened material should be resealed and stored at room temperature. Use of fresh paste daily is highly recommended.

Stencil life/open time are end-user specific. Solder paste performance degrades over time. The condition of the paste should be continually monitored to ensure viability for the application. Environmental conditions, equipment settings and application requirements will impact the useful life of the material. Exposure to heat, moisture and the atmosphere will accelerate paste degradation and should be controlled.

Paste performance can be affected by under-stencil wipe solvent. Isopropanol (IPA) is not recommended. AIM DJAW-10 is recommended for use with all AIM pastes.

ENVIRONMENTAL CONDITIONS



For optimal results, the production area should be maintained at temperature of 22°- 26°C (72°-80°F) at 45% ± 5% relative humidity. If temperature and humidity conditions are not maintained at optimal levels, paste performance may decrease.

Defects such as visible dryness, thickening, transfer efficiency variability, aperture clogging and slumping are indicators that the paste is has degraded beyond its useful life. The paste should be removed, stencil and print area cleaned and new paste applied.

The importance of solder paste cannot be overstated, as it is the foundation of the SMT process. Adherence to these guidelines ensures the solder paste will perform as designed, providing the best possible performance and outcomes. Contact AIM for additional information.

The information provided above is general guidelines for handling AIM Print and Dispense Solder Pastes.

Product Technical Data Sheets (TDS) and Certificate of Analysis should be referenced for specific product recommendations.

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